

REMARKS

This is in response to the Office Action dated September 29, 2004. Claims 1, 5 and 14-16 are pending.

Claim 1 stands rejected under 35 U.S.C. Section 102(b) as being allegedly anticipated by each of Pellerin (EP '954) and Drummond. These Section 102(b) rejections are respectfully traversed for at least the following reasons.

Claim 1 as amended requires "an upper die and a lower die provided with a cavity into which a liquid resin is injected to form the resin upon curing; a resin inlet provided within the upper die to inject the liquid resin into the cavity; and a first air vent through which air within the cavity and the resin inlet is released to an exterior space of the resin molding die when the liquid resin is injected into the cavity by means of *self-weight* thereof." With respect to "self-weight", this means that the pressure applied to the resin is about equal to the pressure inside the die, or in other words, no pressure is applied to the resin for injecting purposes. Self-weight is discussed in the instant specification at page 16, lines 13-18, for example. The use of self-weight injection is advantageous in that there is no need to perform an intense clamping for preventing resin leakage outside the molding, thereby resulting in a possibly simplified production facility and lower overall cost (e.g., pg. 14, lines 14-22).

The cited art fails to disclose or suggest at least the self-weight aspect of claim 1. Instead, in the cited art, a high pressure is applied to the resin for injecting, said pressure being much higher than that inside the die (i.e., high pressure injection is used in the cited art).

Pellerin discloses a method and mold for encapsulating a semiconductor device by resin injection. However, in contrast with claim 1, the injection method of Pellerin is a *high pressure* injection technique where the pressure applied to the resin is much *greater* than the pressure

inside the mold cavity. Thus, Pellerin fails to disclose or suggest the self-weight injection aspect of claim 1.

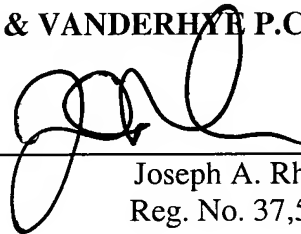
Drummond also uses a high pressure technique, as evidenced in Fig. 3 of Drummond by the horizontal device and the use of clamps tightly pressing the platens together (co. 4, lines 36-49). Since Drummond also uses a high pressure injection process, this reference also fails to disclose or suggest the self-weight aspect of claim 1.

For at least the foregoing reasons, it is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

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